

Title (en)

FUSE LINK, METHOD FOR THE PRODUCTION THEREOF AND SOLDERING SUBSTANCE

Title (de)

SICHERUNGSEINSATZ, VERFAHREN ZU SEINER HERSTELLUNG UND LOTSUBSTANZ

Title (fr)

CARTOUCHE FUSIBLE, SON PROCEDE DE PRODUCTION, AINSI QUE SUBSTANCE DE BRASURE

Publication

EP 1317763 B1 20080514 (DE)

Application

EP 01980371 A 20010911

Priority

- EP 01980371 A 20010911
- EP 0110499 W 20010911
- EP 00119932 A 20000913

Abstract (en)

[origin: EP1189252A1] Fuse insert comprises a molten conductor with a soldering material in a solder depot of a support, the solder being based on tin and the support on copper. The solder contains a tin alloy with a larger first component but smaller than the amount of the tin base material and a second smaller component which does not dissolve in the tin. Crystallization seeds are produced during cooling from liquid into the solid state to form a fine structure. Preferred Features: The soldering material is a tin-bismuth-copper alloy, a tin-indium-copper alloy or a tin-bismuth-iron alloy.

IPC 8 full level

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CPC (source: EP US)

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